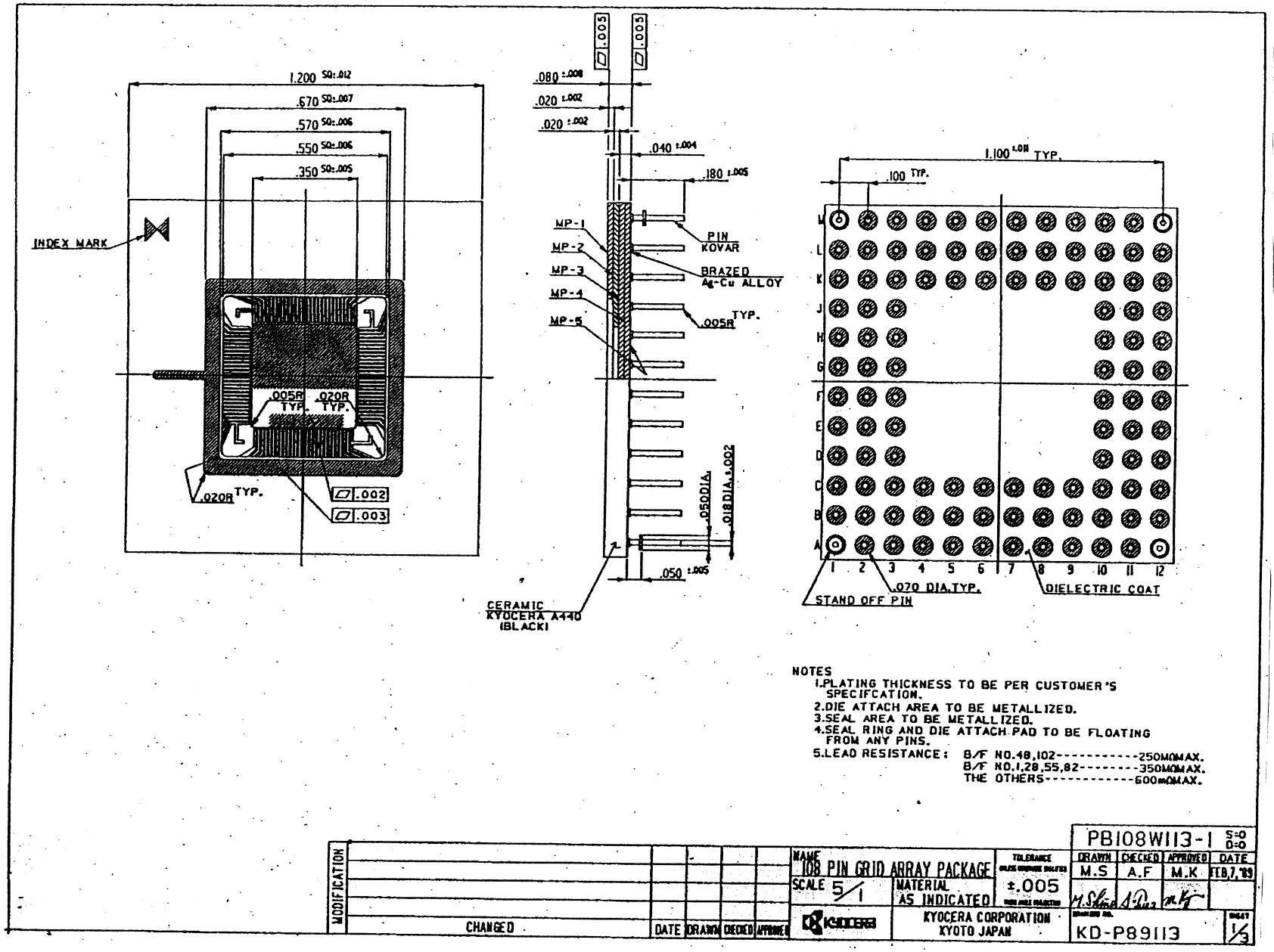
SSM P/N CPG10807



NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFCATION.
2. DIE ATTACH AREA TO BE METALLIZED.
3. SEAL AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: B/F NO.48,102----------250mΩMAX.
   B/F NO.1,28,55,82--------350mΩMAX.
   THE OTHERS----------600mΩMAX.

MODIFICATION					
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME: 108 PIN GRID ARRAY PACKAGE
SCALE 5/1
MATERIAL AS INDICATED
TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION
KYOCERA CORPORATION KYOTO JAPAN
DRAWING NO. KD-P89113

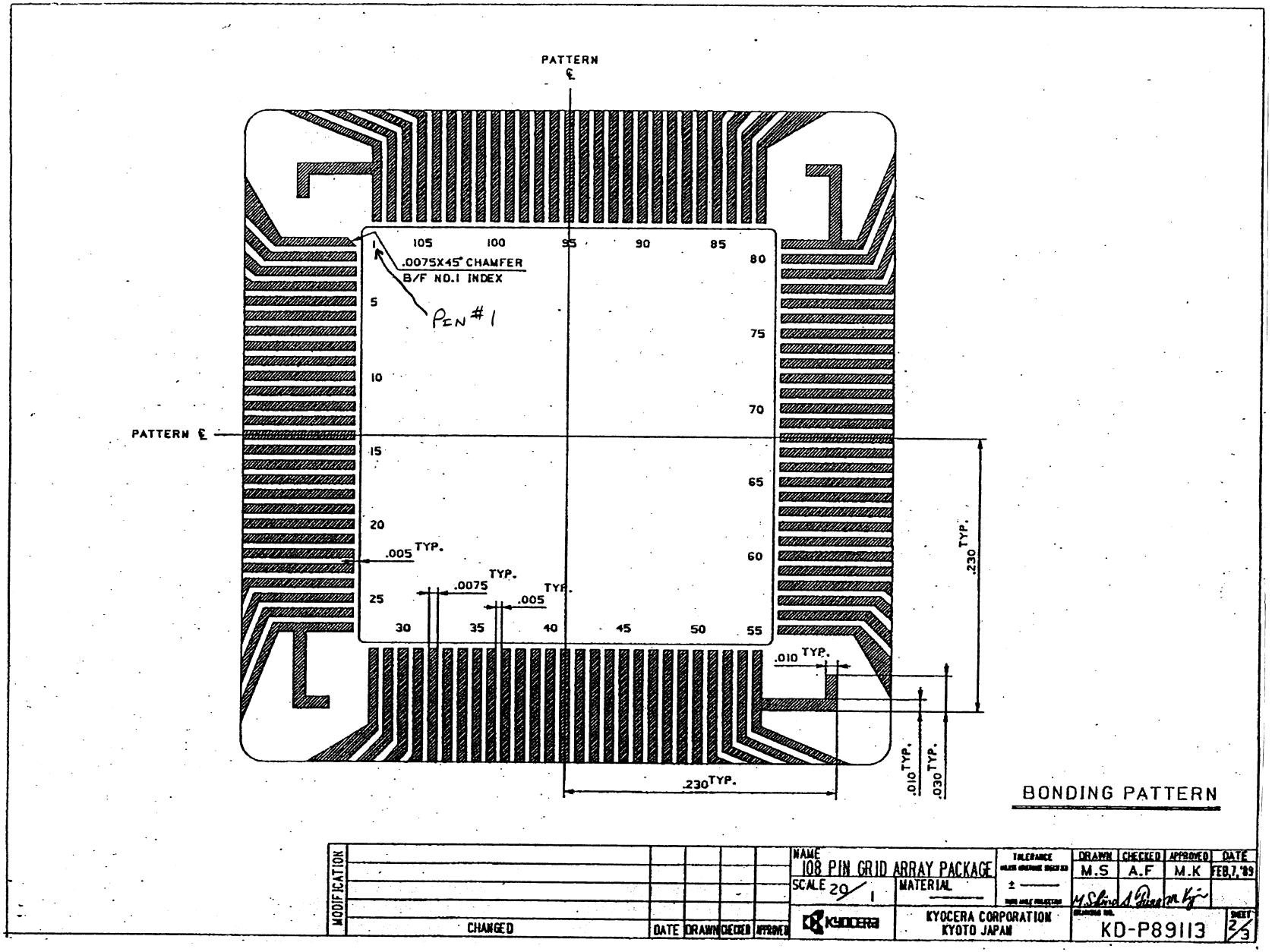
PB108W113-1 S:0 D:0

DRAWN	CHECKED	APPROVED	DATE
M.S	A.F	M.K	FEB.7,'89

SHEET 1/3

SPECTRUM SEMICONDUCTOR MATERIALS, INC.
www.spectrum-semi.com Phone: 408-435-5555 Fax: 408-435-8226

SSM P/N CPG10807



SSM P/N CPG10807

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.
1	M12
2	L11
3	L12
4	K11
5	K12
6	J10
7	J11
8	J12
9	H10
10	H11
11	H12
12	G10
13	G11
14	G12
15	F10
16	F11
17	F12
18	E10
19	E11
20	E12

W/B NO.	PIN NO.
21	D10
22	D11
23	D12
24	C10
25	C11
26	C12
27	B12
28	A12
29	B11
30	A11
31	B10
32	A10
33	C9
34	B9
35	A9
36	C8
37	B8
38	A8
39	C7
40	B7

W/B NO.	PIN NO.
41	A7
42	C6
43	B6
44	A6
45	C5
46	B5
47	A5
48	C4
49	B4
50	A4
51	C3
52	B3
53	A3
54	A2
55	A1
56	B2
57	B1
58	C2
59	C1
60	D3

W/B NO.	PIN NO.
61	D2
62	D1
63	E3
64	E2
65	E1
66	F3
67	F2
68	F1
69	G3
70	G2
71	G1
72	H3
73	H2
74	H1
75	J3
76	J2
77	J1
78	K3
79	K2
80	K1

W/B NO.	PIN NO.
81	L1
82	M1
83	L2
84	M2
85	L3
86	M3
87	K4
88	L4
89	M4
90	K5
91	L5
92	M5
93	K6
94	L6
95	M6
96	K7
97	L7
98	M7
99	K8
100	L8

W/B NO.	PIN NO.
101	M8
102	K9
103	L9
104	M9
105	K10
106	L10
107	M10
108	M11

S/R	NC
D/A	NC

MODIFICATION	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME: 108 PIN GRID ARRAY PACKAGE
SCALE: X
MATERIAL: —
TOLERANCE (UNLESS OTHERWISE SPECIFIED): ± —
THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
M.S	A.F	M.K	FEB,7,'89

KYOCERA
KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO. KD-P89113
SHEET 3/3